

	Typ e	L #	Hits	Search Text	DBs
1	BRS	L1	141444	"438"/\$.ccls.	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
2	BRS	L2	576	1 and solid-state near (imag\$3 or device)	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
3	BRS	L3	1	2 and base near flatness	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
4	BRS	L4	71	2 and base	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
5	BRS	L5	8	4 and flatness	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
6	BRS	L7	0	5 and position\$3 near hole?	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
7	BRS	L8	1	2 and mold?	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
8	BRS	L1 0	26	(minamio-masanori or horiki-hiroshi or nishio-tetshuhi).in.	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
9	BRS	L1 1	0	10 and solid-state near (imag\$3 or device)	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
10	BRS	L1 2	0	10 and CCD	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
11	BRS	L1 3	2072	((solid-state or (solid near state)) near imaging).ti.	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
12	BRS	L1 4	0	13 and base near flatness	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
13	BRS	L1 5	3	13 and mold?	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
14	BRS	L1 6	4	13 and position\$3 near hole?	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
15	BRS	L1 7	2	16 and mold\$3	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
16	BRS	L1 8	6928	((solid-state or (solid near state) or CCD) near imaging)	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
17	BRS	L2 0	260	18 and mold\$3	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
18	BRS	L2 1	50	20 and tape	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
19	BRS	L2 3	1	22 and curing	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB

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20	BRS	L2 4	0	22 and position\$3 near hole?	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
21	BRS	L2 2	5	21 and resin near mold\$3	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB